NOTES:
1. SOLDERING TO BE IN ACCORDANCE WITH NASA SPECIFICATION NAS-STD-8739.2 AND NASA-STD-8739.3.
2. IC PATTERNS FOR U11-13 WERE UPDATED. LEADS WERE REWORKED AT MITE CENTER LEADS ON PADS PRIOR TO SOLDERING.
3. IC IS STATIC SENSITIVE. HANDLE IC W/I MITE PROCEDURE 99-01003 OR EQUIVALENT.
4. EVENLY SPACE ALL SMD'S ON PADS PRIOR TO SOLDERING.
   ▲ DON'T INSTALL TEST HEADERS (HH-115)
   ▲ EPOXY Q2 AND U1 TO THE BOARD USING P/N 17. EPOXY LAYER TO BE AS THIN AS POSSIBLE.
   ▲ SPACE Q2.3 AND U17 OFF P/N 1.0357. ENSURE CASING DO NOT TOUCH ADJACENT COMPONENTS.
   ▲ PARTS TO RECEIVE CURSORY VISUAL INSPECTION PRIOR TO INSTALLATION.
   ▲ ATTACH P1 TO PCB WITH SUPPLIED HARDWARE AND TORQUE TO 32 IN OZ PRIOR TO SOLDERING TO PCB.